

AK P-Channel Trench Power MOSFET

Features

- P-channel
- $V_{DS} = -30V, I_D = -50A$
 $R_{DS(ON)} < 11m\Omega @ V_{GS} = -10V$
- Pb-free lead plating; RoHS compliant

Application

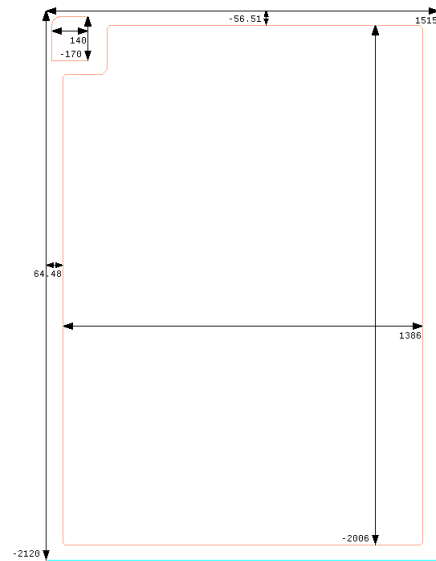
- Load Switch
- PWM Application
- Power management

30V P-Ch Power MOSFET

Parameter	Value	Unit
V_{DS}	-30	V
$R_{DS(on),typ}$	$V_{GS} = -10V$	7.2 m Ω
$R_{DS(on),typ}$	$V_{GS} = -4.5V$	11 m Ω
I_{D_MAX}	-50	A

Physical Characteristics:

Wafer Size (inch)	8
Chip Size with scribe line (mm)	1.575x2.180
Wafer Thickness (mil)	6
Top Metal	AlCu
Top Metal Thickness (μm)	4
Back Metal	Ti/Ni/Ag
Scribe Line (μm)	60
Gate Wire recommended	42 μm Cu
Source Wires recommended	$\Phi 12$ mil AL*2
Gross Die	8211
Source Pad Dimensions(μm)	1386*2006
Gate Pad Dimensions(μm)	140*170



GQ004 PAD G: 140 X170 S: 1386 X 2006

Electrical Characteristics at T_j=25°C (unless otherwise specified)

Parameter	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Drain to Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250μA	-30	-35		V
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =-250μA	-1.0	-1.6	-2.5	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} =0V, V _{DS} =-30V, T _j =25°C	-	-	-1	μA
Gate to Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Drain to Source on Resistance	R _{DS(on)}	V _{GS} =10V, I _D =-20A	-	7.2	11	mΩ
		V _{GS} =4.5V, I _D =-15A	-	11	16	
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	6.5	-	Ω